

11-18-1998



FORM PTO-1595
1-31-92

RE 100903894
PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office
Attorney Docket No: TSAI112525

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Names of conveying party:
Kao-Hsing Wang
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party:
Name: Vanguard International Semiconductor Corporation
Address: 123, Park Ave-3rd., Science-Based Industrial Park

3. Nature of conveyance: MD11-10-98
 Assignment Merger
 Security Agreement Change of Name
 Other
Execution date: July 3, 1998

City: Hsinchu Province: Taiwan
Country: R.O.C.
Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
A. Patent Application No(s). 09/189741 | B. Patent No(s).
Additional numbers attached? Yes No

If this document is being filed together with a new application, the execution date of the application is: July 3, 1998

5. Name and address of party to whom correspondence concerning document should be mailed:

Chun M. Ng, Esq.
CHRISTENSEN O'CONNOR
JOHNSON & KINDNESS^{PLLC}
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Suite 2800
Seattle, WA 98101-2347
(206) 682-8100

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. 3.41): \$ 40.00
Check No. 100788 in the amount of \$40.00 is enclosed.

8. The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account Number 03-1740.

DO NOT USE THIS SPACE

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Chun M. Ng
Name of Attorney or Agent
Registration No. 36,878
Direct Dial (206) 224-0719

Signature

November 10, 1998
Date

Total number of pages including cover sheet, attachments and document: 3

OMB No. 0651-0011 (exp. 4/94)

11/18/1998 DNGUYEN 00000060 09189741
01 FC:581 40.00 OP

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
PLANARIZATION FOR INTERLAYER DIELECTRIC

The PATENT RIGHTS referred to in this agreement are:

(check one) a patent application for this invention, executed by the ASSIGNOR(S)
 concurrently with this assignment.

U.S. patent application Serial No. _____ filed _____

a U.S. patent application based on PCT International Application
 No. _____ filed on (date) _____ (U.S. patent application
 Serial No. _____, if known).

U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions reissues, continuations and extensions of
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one) U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to
 claim the benefit of the filing date of any U.S. or foreign patent application
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) VANGUARD INTERNATIONAL SEMICONDUCTOR CORPORATION

(Address) 123, PARK AVE-3RD., SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,
TAIWAN, R.O.C.

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
 provisions, based on any earlier patent applications for this invention.

ASSIGNEE: VANGUARD INTERNATIONAL SEMICONDUCTOR CORPORATION

INVENTION TITLE: PLANARIZATION FOR INTERLAYER DIELECTRIC

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorizes(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorizes(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Kao-Hsing WANG

Name of sole or first inventor

Kao-Hsing Wang
Signature

11/13/98
Date

Name of second inventor, if any

Signature

Date

Name of third inventor, if any

Signature

Date

Name of fourth inventor, if any

Signature

Date

Name of fifth inventor, if any

Signature

Date

Name of sixth inventor, if any

Signature

Date

Name of seventh inventor, if any

Signature

Date

Name of eighth inventor, if any

Signature

Date